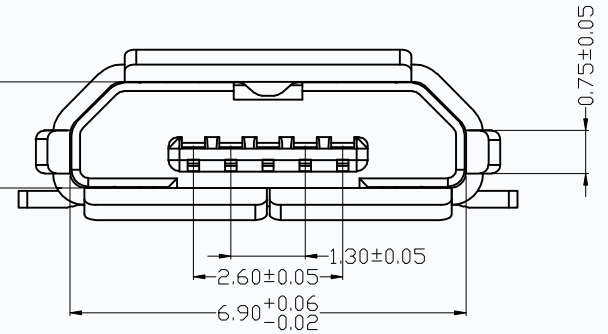
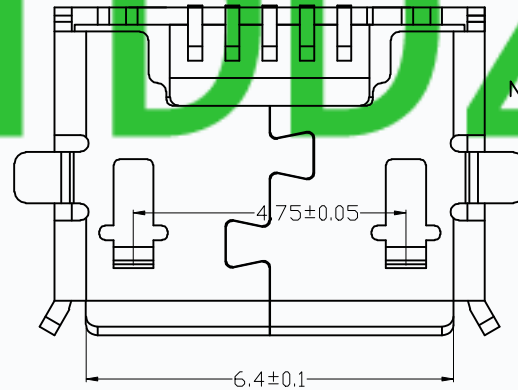
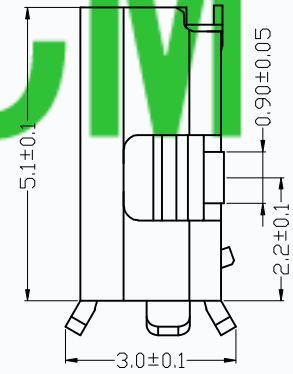
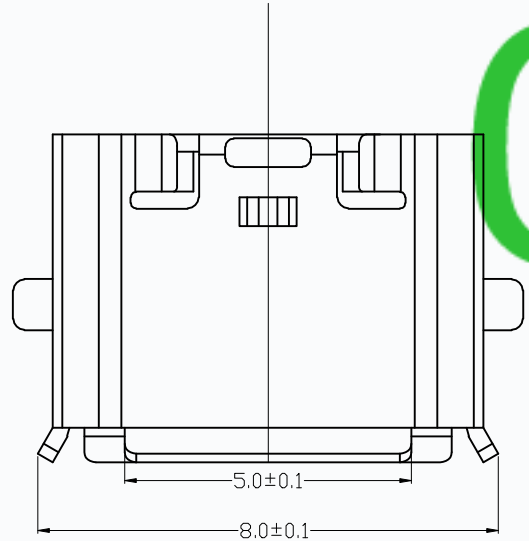
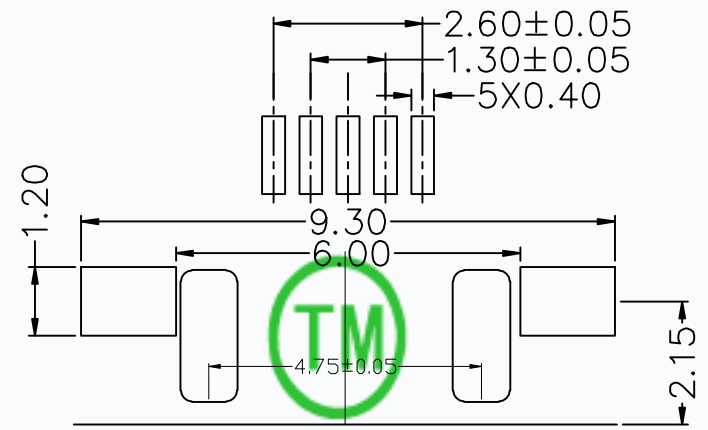
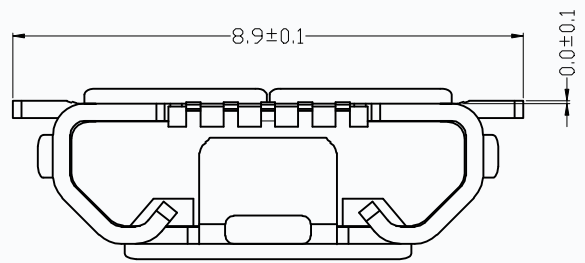


修改序号	修改说明	签名	日期
A/0			



CMTDDZ

PCB LAYOUT

- Note:
1. Material:
    - 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
    - 1.2 Contact: copper alloy,t=0.15mm
    - 1.3 Shell: copper alloy&SUS
  2. Specification:
    - 2.1 Current rating: 1 A Max.
    - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
    - 2.3 Contact resistance: 30 mΩ Max.
    - 2.4 Insulation resistance: 100 MΩ Min.
    - 2.5 Total mating force: 3.57 Kgf Max.
    - 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
    - 2.7 Temperature range: -30°C~80°C

尺寸	允许公差
X.	±0.50
.X	±0.20
.XX	±0.10
.XXX	±0.03
角度	±1.00°

**东莞市田都电子有限公司**  
DONGGUAN TIANDU ELECTRONIC CO.,LTD

<b>图纸类型</b>		<b>图纸名称:</b>	
产品工程图		MICRO 5P/F B 反向两脚SMT无柱卷边	
设计	2011.07.21	产品料号	T10-05FX01
审核		视图	版号: A/0